

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (Ultra High speed U-MOSIII)

# TPCP8001-H

High Efficiency DC/DC Converter Applications  
 Notebook PC Applications  
 Portable Equipment Applications

- Small footprint due to a small and thin package
- High speed switching
- Small gate charge:  $Q_{SW} = 3.6 \text{ nC (typ.)}$
- Low drain-source ON-resistance:  $R_{DS(ON)} = 13 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance:  $|Y_{fs}| = 16 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = 10 \text{ }\mu\text{A (max) (}V_{DS} = 30\text{V)}$
- Enhancement mode:  $V_{th} = 1.1 \text{ to } 2.3 \text{ V (}V_{DS} = 10 \text{ V, } I_D = 1 \text{ mA)}$

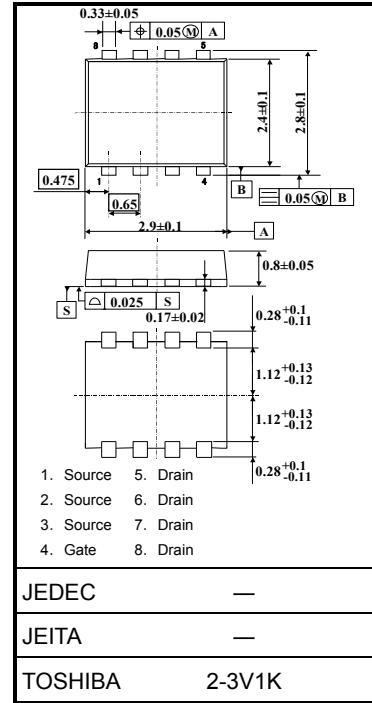
### Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	30	V
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	30	V
Gate-source voltage		$V_{GSS}$	$\pm 20$	V
Drain current	DC (Note 1)	$I_D$	7.2	A
	Pulsed (Note 1)	$I_{DP}$	28.8	
Drain power dissipation (t = 5 s) (Note 2a)		$P_D$	1.68	W
Drain power dissipation (t = 5 s) (Note 2b)		$P_D$	0.84	W
Single-pulse avalanche energy (Note 3)		$E_{AS}$	33.6	mJ
Avalanche current		$I_{AR}$	7.2	A
Repetitive avalanche energy (Note 2a) (Note 4)		$E_{AR}$	0.066	mJ
Channel temperature		$T_{ch}$	150	°C
Storage temperature range		$T_{stg}$	-55 to 150	°C

Note: For Notes 1 to 5, refer to the next page.

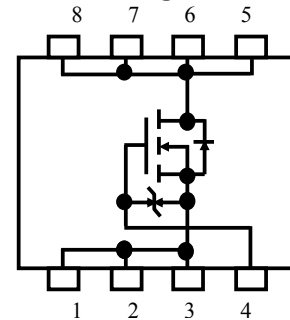
This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm

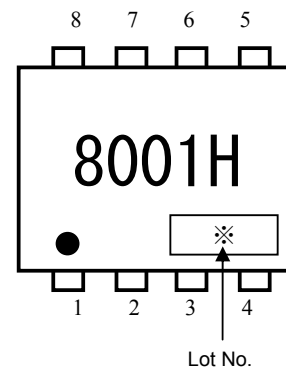


Weight: 0.017 g (typ.)

### Circuit Configuration



### Marking (Note 5)

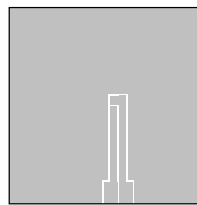


## Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	$R_{th(ch-a)}$	74.4	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	$R_{th(ch-a)}$	148.8	°C/W

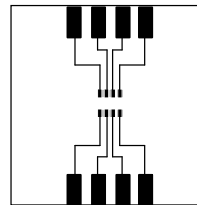
Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



(a)

FR-4  
25.4 × 25.4 × 0.8  
(Unit: mm)



(b)

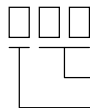
FR-4  
25.4 × 25.4 × 0.8  
(Unit: mm)

Note 3:  $V_{DD} = 24\text{ V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 0.5\text{ mH}$ ,  $R_G = 25\ \Omega$ ,  $I_{AR} = 7.2\text{ A}$

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: ● on the lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)



Week of manufacture

(01 for first week of the year, continuing up to 52 or 53)

Year of manufacture

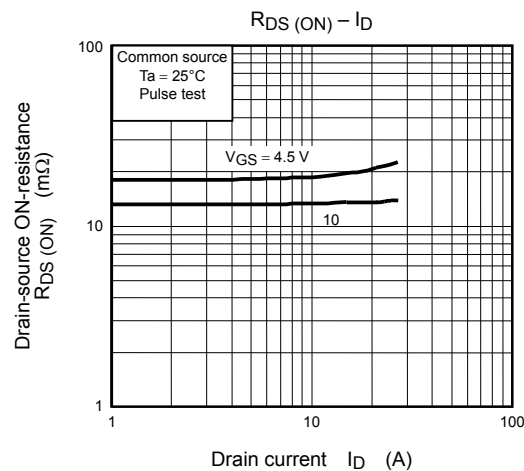
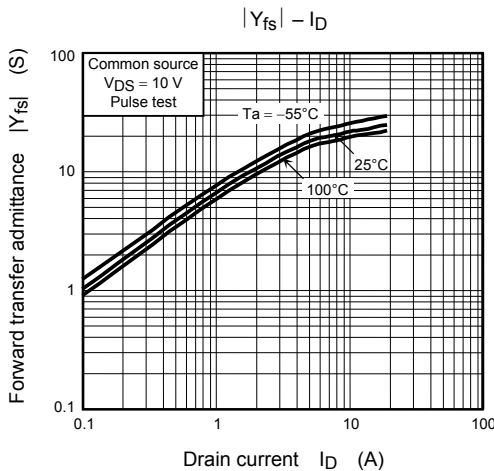
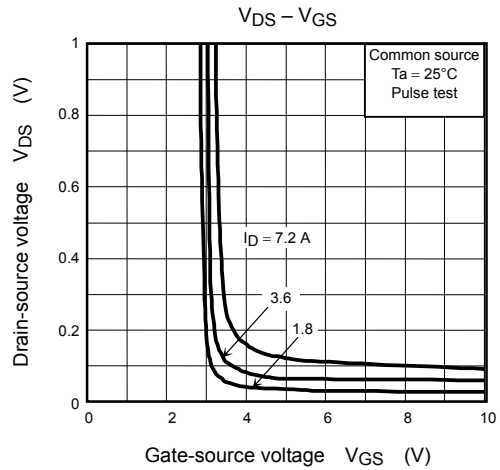
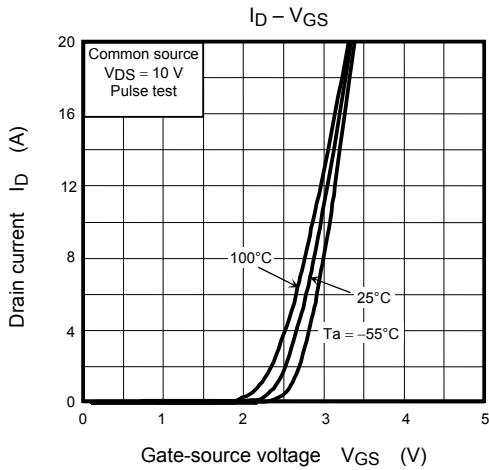
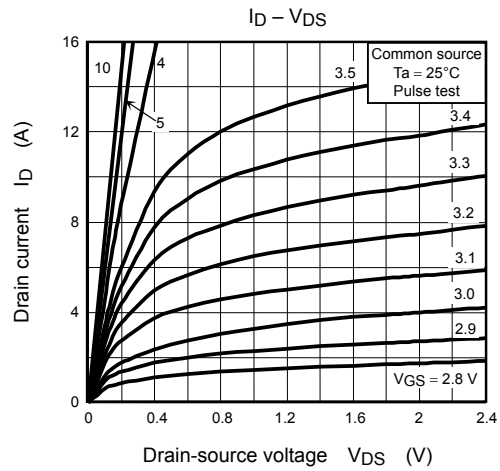
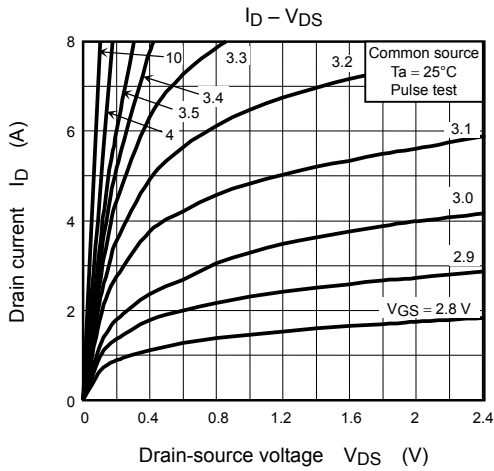
(The last digit of the calendar year)

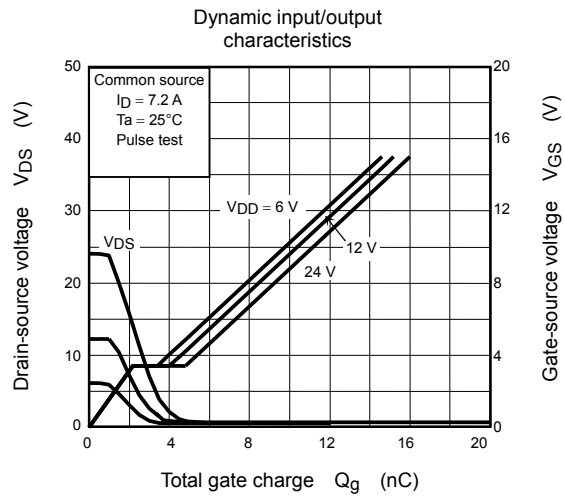
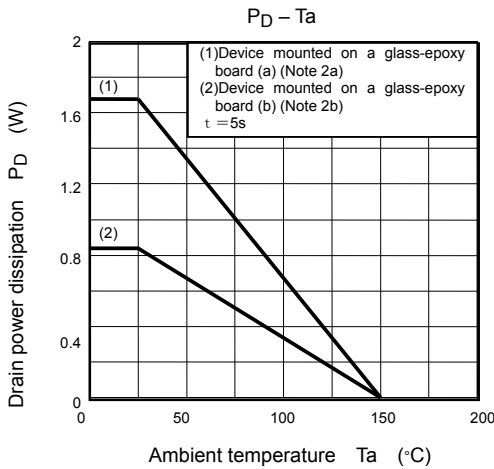
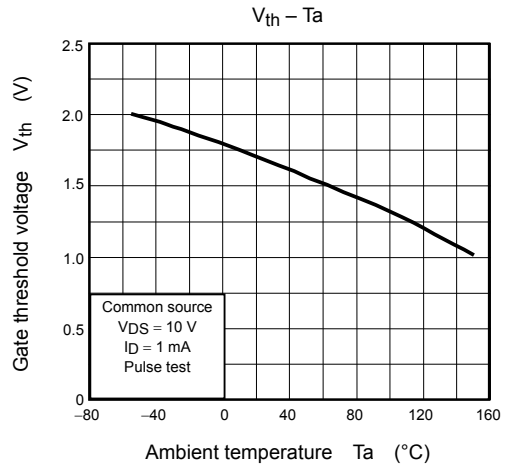
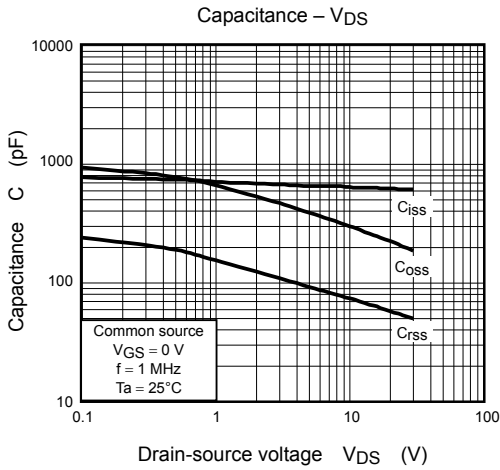
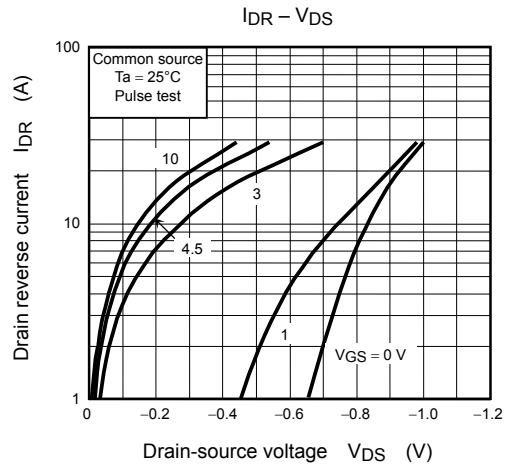
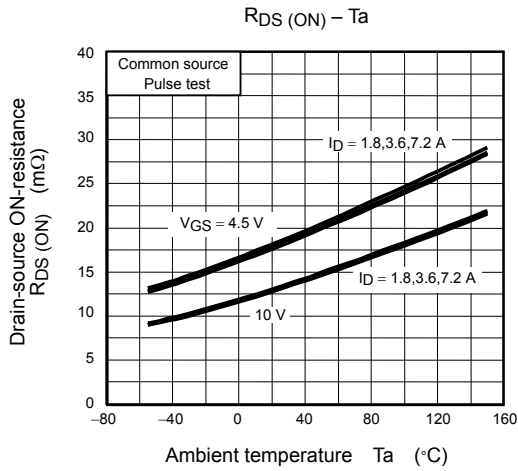
## Electrical Characteristics (Ta = 25°C)

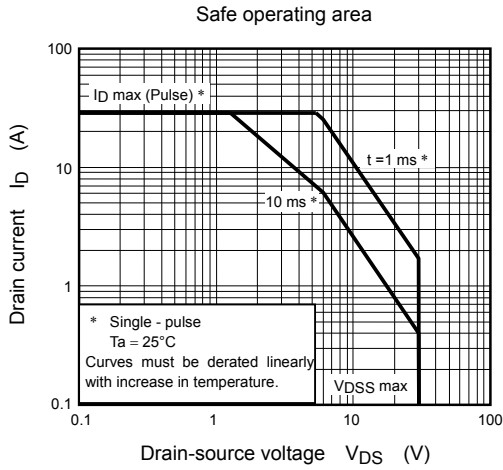
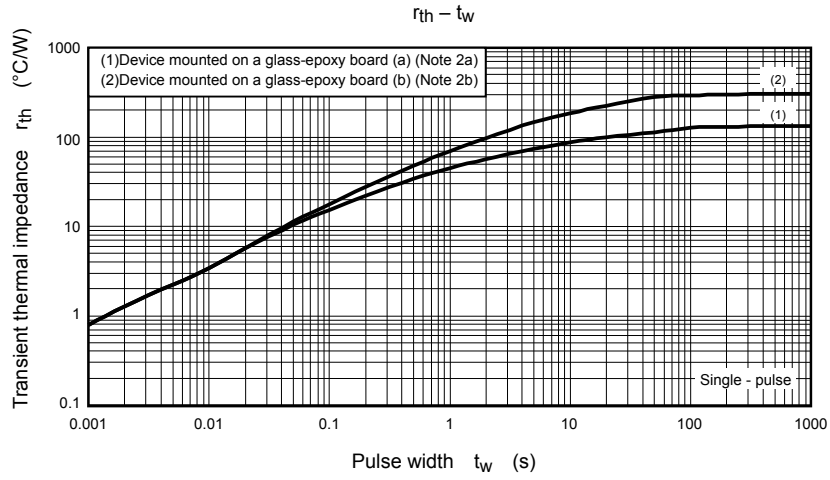
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0\text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Drain cutoff current		$I_{DSS}$	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	$\mu\text{A}$
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	30	—	—	V
		$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -20\text{ V}$	15	—	—	
Gate threshold voltage		$V_{th}$	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	1.1	—	2.3	V
Drain-source ON-resistance		$R_{DS(ON)}$	$V_{GS} = 4.5\text{ V}, I_D = 3.6\text{ A}$	—	19	25	$\text{m}\Omega$
			$V_{GS} = 10\text{ V}, I_D = 3.6\text{ A}$	—	13	16	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 3.6\text{ A}$	8	16	—	S
Input capacitance		$C_{iss}$	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	640	—	pF
Reverse transfer capacitance		$C_{riss}$		—	75	—	
Output capacitance		$C_{oss}$		—	300	—	
Switching time	Rise time	$t_r$		—	4	—	ns
	Turn-on time	$t_{on}$		—	8	—	
	Fall time	$t_f$		—	4	—	
	Turn-off time	$t_{off}$		—	18	—	
Total gate charge (gate-source plus gate-drain)		$Q_g$	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 7.2\text{ A}$	—	11	—	nC
			$V_{DD} \approx 24\text{ V}, V_{GS} = 5\text{ V}, I_D = 7.2\text{ A}$	—	6.3	—	
Gate-source charge 1		$Q_{gs1}$	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 7.2\text{ A}$	—	2.2	—	
Gate-drain ("Miller") charge		$Q_{gd}$	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 7.2\text{ A}$	—	2.6	—	
Gate switch charge		$Q_{sw}$	$V_{DD} \approx 24\text{ V}, V_{GS} = 10\text{ V}, I_D = 7.2\text{ A}$	—	3.6	—	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	$I_{DRP}$	—	—	—	28.8	A
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = 7.2\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	V







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